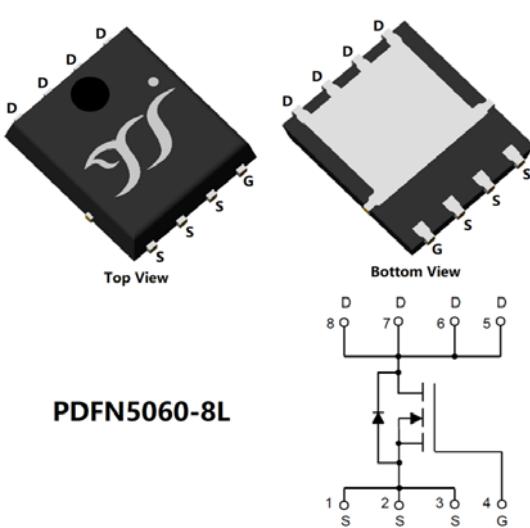


## N-Channel Enhancement Mode Field Effect Transistor



### Product Summary

- $V_{DS}$  100V
- $I_D$  60A
- $R_{DS(ON)}$  (at  $V_{GS}=10V$ ) <12 mohm
- $R_{DS(ON)}$  (at  $V_{GS}=4.5V$ ) <15 mohm
- 100% UIS Tested
- 100%  $\nabla V_{DS}$  Tested

### General Description

- Split gate trench MOSFET technology
- Excellent package for heat dissipation
- High density cell design for low  $R_{DS(ON)}$
- Part no. with suffix "Q" means AEC-Q101 qualified

### Applications

- High Frequency Switching
- Synchronous Rectification
- 12V, 24V and 48V Automotive systems

### ■ Absolute Maximum Ratings ( $T_A=25^\circ C$ unless otherwise noted)

Parameter		Symbol	Limit	Unit
Drain-source Voltage		$V_{DS}$	100	V
Gate-source Voltage		$V_{GS}$	$\pm 20$	V
Drain Current	$T_c=25^\circ C$	$I_D$	60	A
	$T_c=125^\circ C$		28	
Pulsed Drain Current <sup>A</sup>		$I_{DM}$	240	A
Avalanche energy <sup>B</sup>		EAS	200	mJ
Total Power Dissipation <sup>C</sup>	$T_c=25^\circ C$	$P_D$	78	W
	$T_c=125^\circ C$		15	
Junction and Storage Temperature Range		$T_J, T_{STG}$	-55~+150	°C

### ■ Thermal resistance

Parameter		Symbol	Typ	Max	Units
Thermal Resistance Junction-to-Ambient <sup>D</sup>	Steady-State	$R_{\theta JA}$	92	100	°C/W
Thermal Resistance Junction-to-Case	Steady-State	$R_{\theta JC}$	1.3	1.6	

### ■ Ordering Information (Example)

PREFERRED P/N	PACKING CODE	Marking	MINIMUM PACKAGE(pcs)	INNER BOX QUANTITY(pcs)	OUTER CARTON QUANTITY(pcs)	DELIVERY MODE
YJG60G10BQ	F1	YJG60G10B	5000	10000	100000	13" reel



# YJG60G10BQ

## ■ Electrical Characteristics ( $T_J=25^\circ\text{C}$ unless otherwise noted)

Parameter	Symbol	Conditions	Min	Typ	Max	Units
<b>Static Parameter</b>						
Drain-Source Breakdown Voltage	$\text{BV}_{\text{DSS}}$	$V_{\text{GS}}=0\text{V}, I_{\text{D}}=250\mu\text{A}$	100			V
Zero Gate Voltage Drain Current	$I_{\text{DSS}}$	$V_{\text{DS}}=100\text{V}, V_{\text{GS}}=0\text{V}$			1	$\mu\text{A}$
Gate-Body Leakage Current	$I_{\text{GSS}}$	$V_{\text{GS}}= \pm 20\text{V}, V_{\text{DS}}=0\text{V}$			$\pm 100$	nA
Gate Threshold Voltage	$V_{\text{GS(th)}}$	$V_{\text{DS}}=V_{\text{GS}}, I_{\text{D}}=250\mu\text{A}$	1	1.8	2.8	V
Static Drain-Source On-Resistance	$R_{\text{DS(ON)}}$	$V_{\text{GS}}=10\text{V}, I_{\text{D}}=20\text{A}$		8.0	12	$\text{m}\Omega$
		$V_{\text{GS}}=4.5\text{V}, I_{\text{D}}=20\text{A}$		9.5	15	$\text{m}\Omega$
Diode Forward Voltage	$V_{\text{SD}}$	$I_{\text{S}}=20\text{A}, V_{\text{GS}}=0\text{V}$			1.3	V
Maximum Body-Diode Continuous Current	$I_{\text{S}}$				60	A
Gate resistance	$R_{\text{G}}$	f=1MHz, Open drain		1		$\Omega$
<b>Dynamic Parameters</b>						
Input Capacitance	$C_{\text{iss}}$	$V_{\text{DS}}=25\text{V}, V_{\text{GS}}=0\text{V}, f=1\text{MHz}$		2500		pF
Output Capacitance	$C_{\text{oss}}$			1385		
Reverse Transfer Capacitance	$C_{\text{rss}}$			45		
<b>Switching Parameters</b>						
Total Gate Charge	$Q_{\text{g}}$	$V_{\text{GS}}=13\text{V}, V_{\text{DS}}=50\text{V}, I_{\text{D}}=30\text{A}$		36.0		nC
Gate-Source Charge	$Q_{\text{gs}}$			6.3		
Gate-Drain Charge	$Q_{\text{gd}}$			13.8		
Reverse Recovery Charge	$Q_{\text{rr}}$	$V_{\text{GS}}=0\text{V}, di/dt=100\text{A}/\mu\text{s}, I_{\text{S}}=30\text{A}$		280		ns
Reverse Recovery Time	$t_{\text{rr}}$			10.5		
Turn-on Delay Time	$t_{\text{D(on)}}$			12		
Turn-on Rise Time	$t_{\text{r}}$	$V_{\text{GS}}=13\text{V}, V_{\text{DD}}=50\text{V}, I_{\text{DS}}=30\text{A}$ $R_{\text{GEN}}=2.3\Omega$		62		ns
Turn-off Delay Time	$t_{\text{D(off)}}$			24.5		
Turn-off fall Time	$t_{\text{f}}$			3.5		

- A. Repetitive rating; pulse width limited by max. junction temperature.
  - B.  $V_{\text{DD}}=50\text{V}$ ,  $R_{\text{G}}=25\Omega$ ,  $L=1\text{mH}$ ,  $I_{\text{AS}}=20\text{A}$
  - C.  $P_d$  is based on max. junction temperature, using junction-case thermal resistance.
  - D. The value of  $R_{\thetaJA}$  is measured with the device mounted on the minimum recommend pad size, in the still air environment with  $T_A = 25^\circ\text{C}$ .
- The maximum allowed junction temperature of  $150^\circ\text{C}$ . The value in any given application depends on the user's specific board design.



## ■ Typical Performance Characteristics

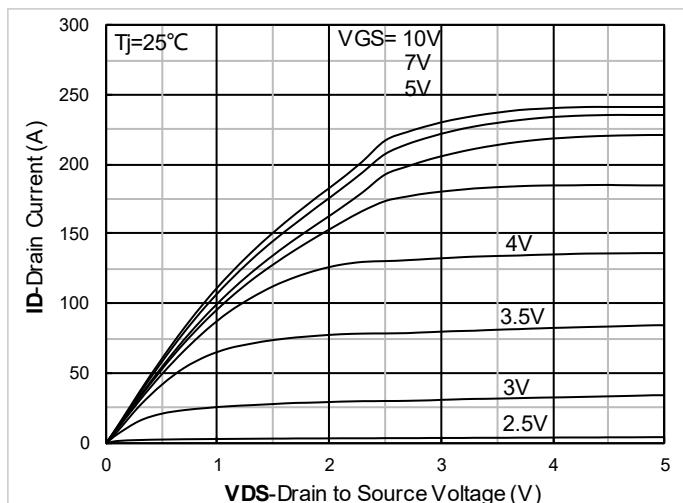


Figure 1. Output Characteristics

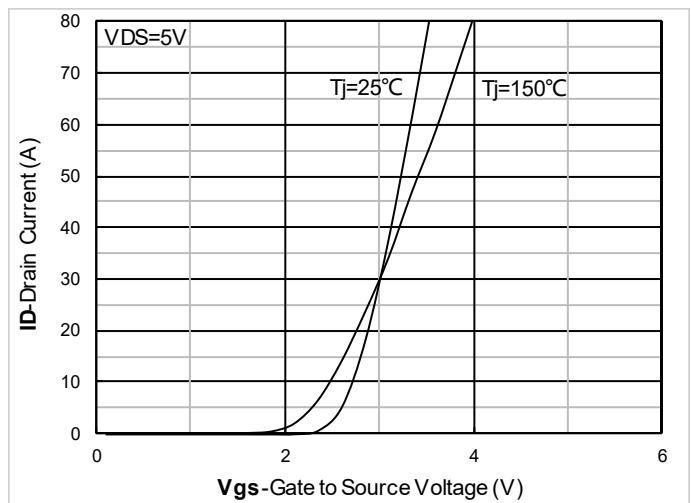


Figure 2. Transfer Characteristics

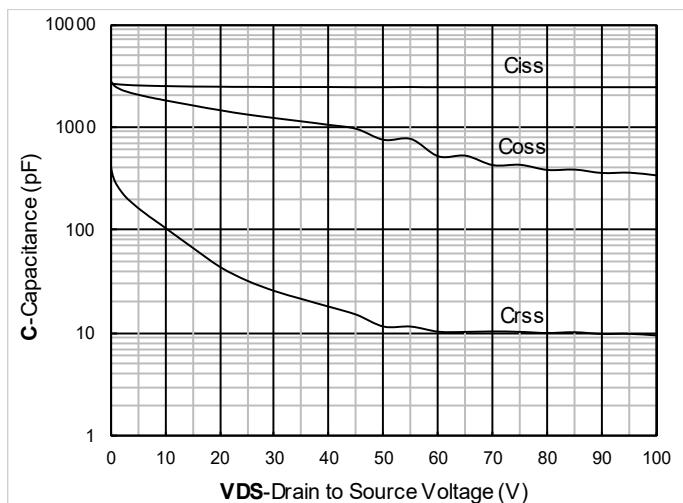


Figure 3. Capacitance Characteristics

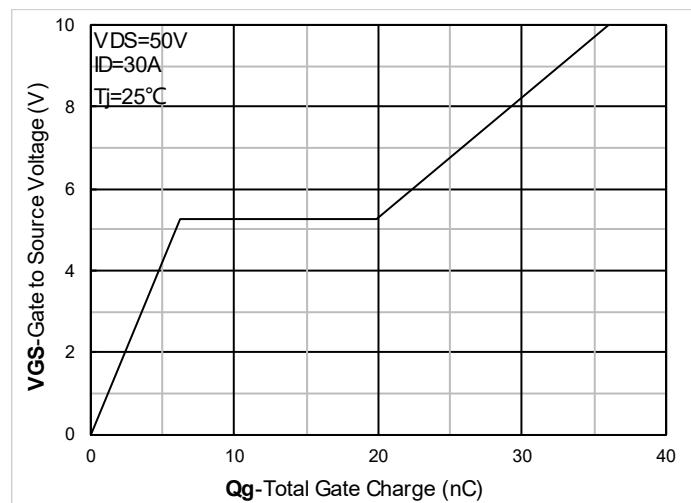


Figure 4. Gate Charge

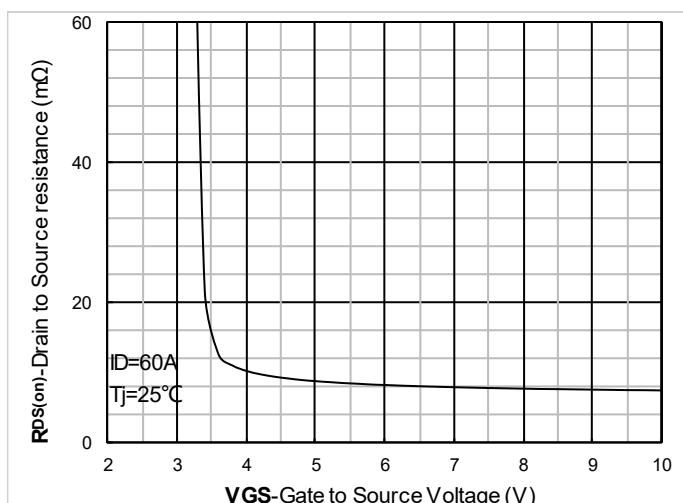


Figure 5. On-Resistance vs Gate to Source Voltage

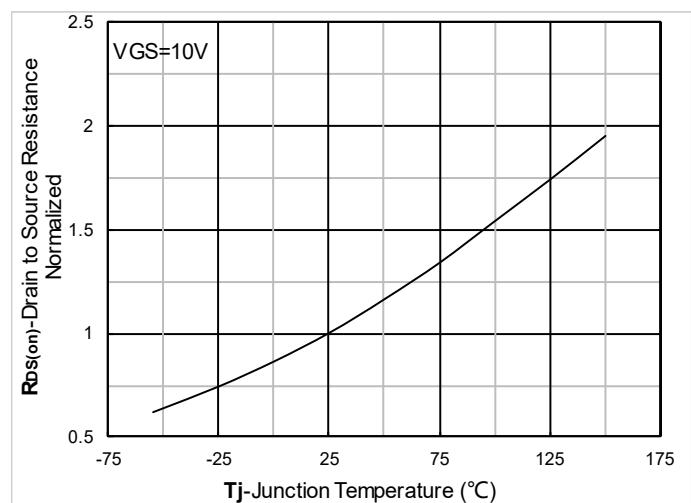


Figure 6. Normalized On-Resistance

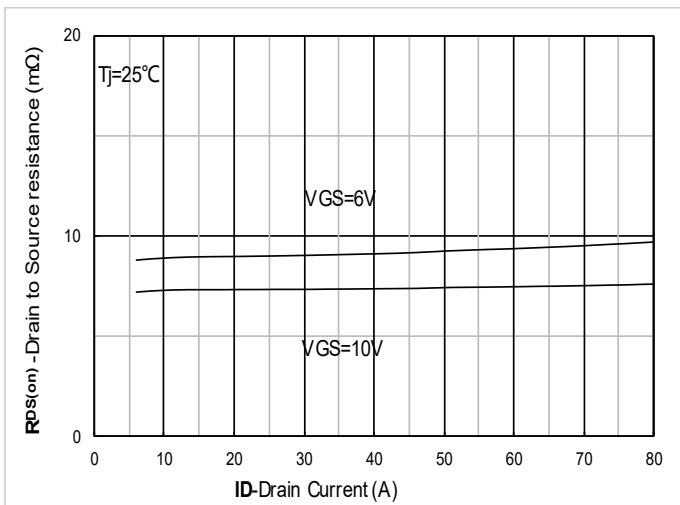
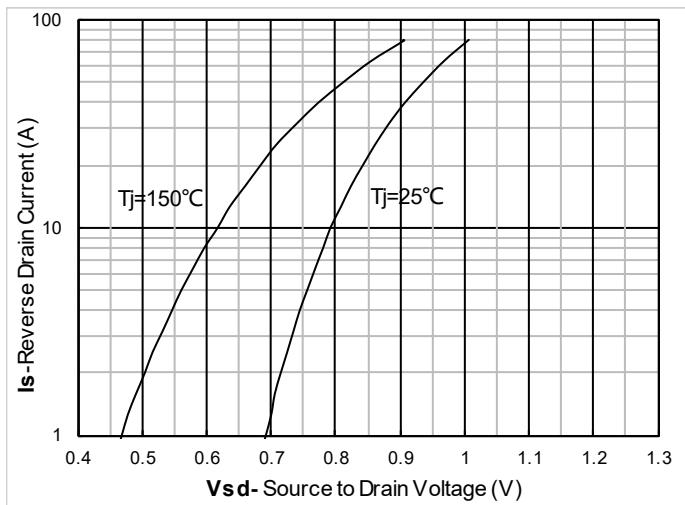
Figure 7.  $R_{DS(on)}$  VS Drain Current

Figure 8. Forward characteristics of reverse diode

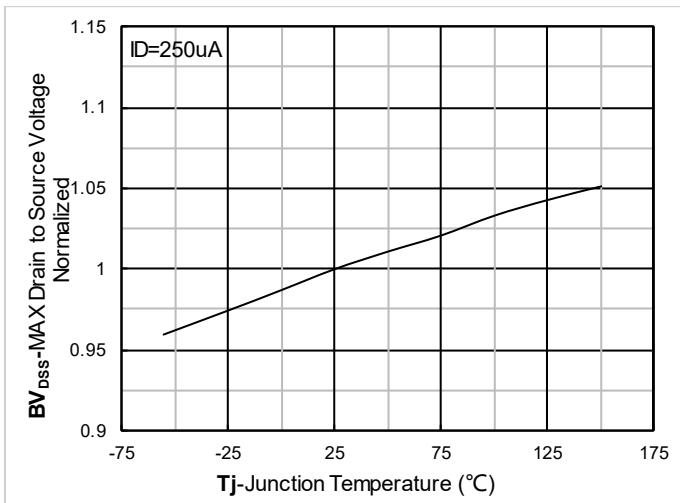


Figure 9. Normalized breakdown voltage

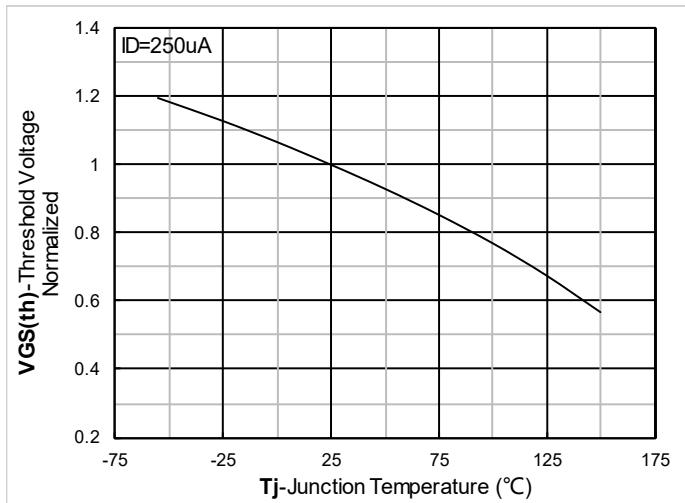


Figure 10. Normalized Threshold voltage

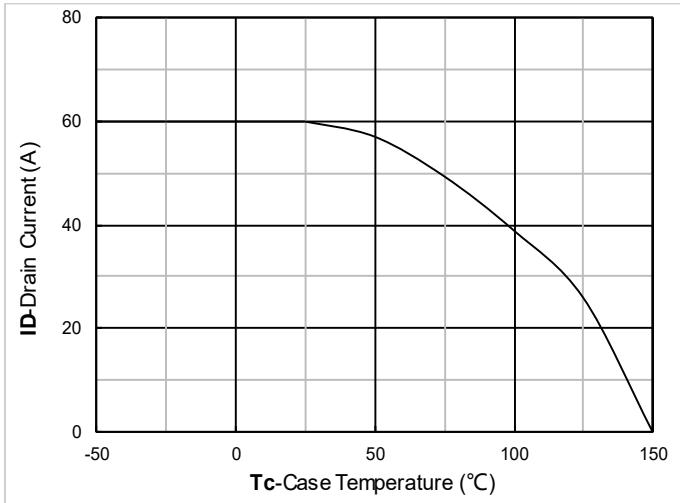


Figure 11. Current dissipation

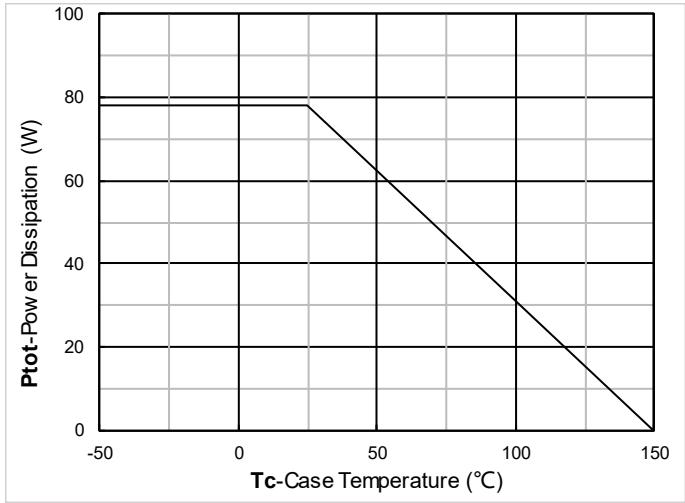


Figure 12. Power dissipation

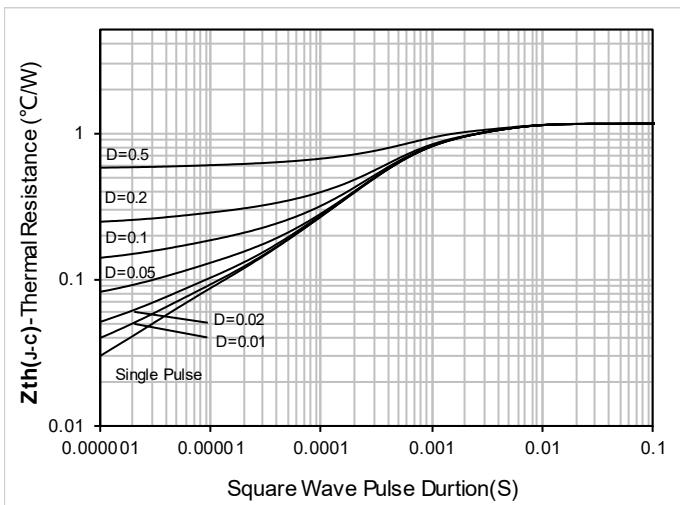


Figure 13. Maximum Transient Thermal Impedance

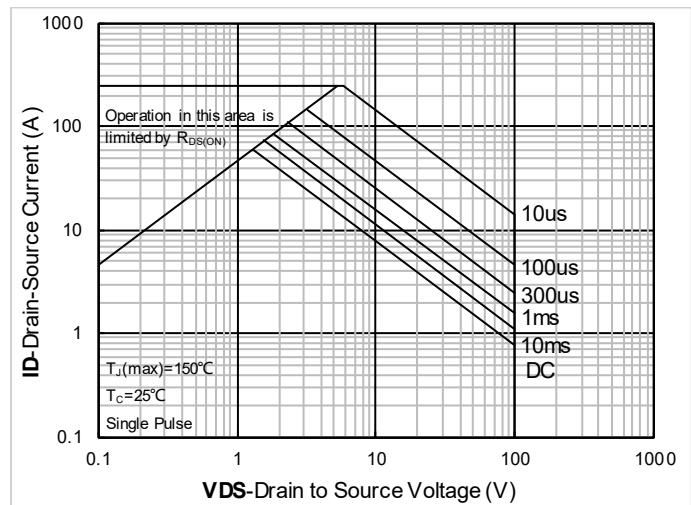


Figure 14. Safe Operation Area

## ■ Test Circuits & Waveforms

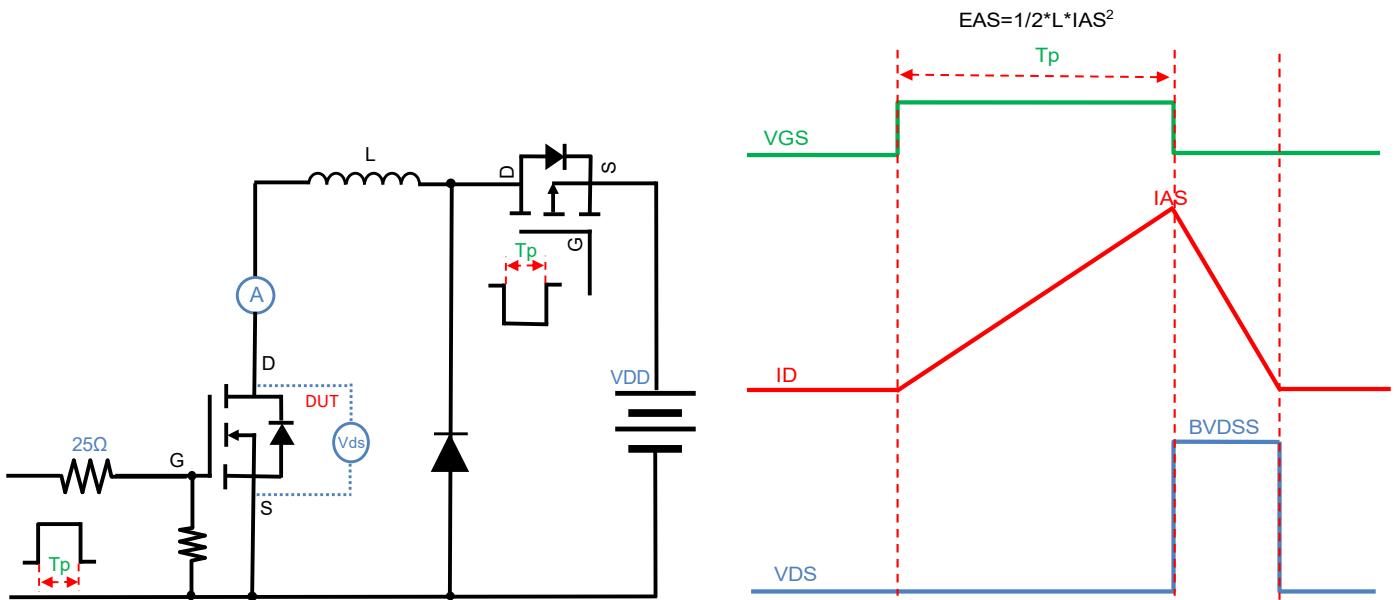


Figure A. Unclamped Inductive Switching (UIS) Test Circuit & Waveform

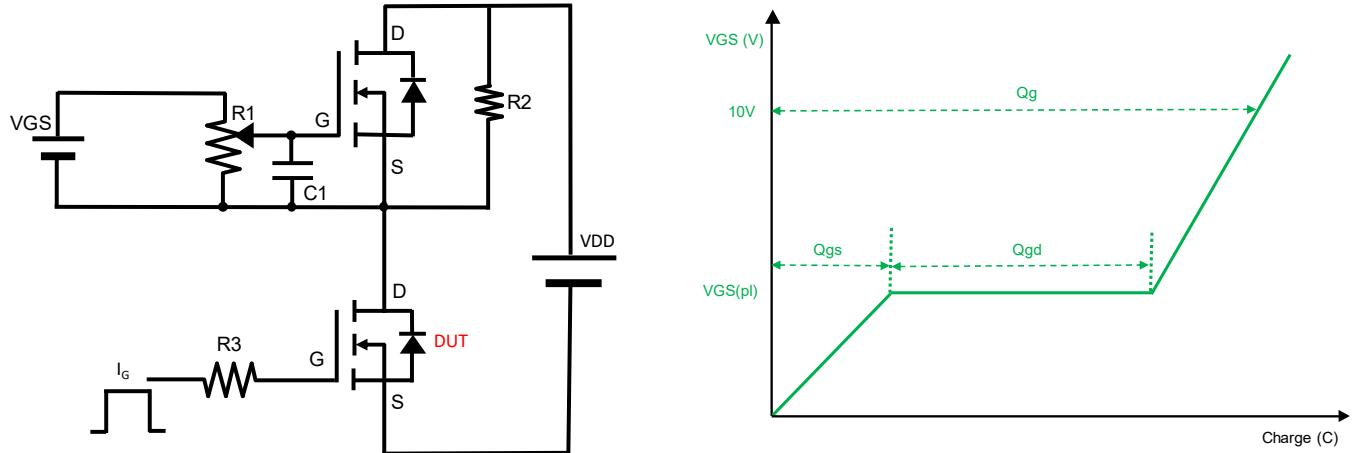


Figure B. Gate Charge Test Circuit & Waveform

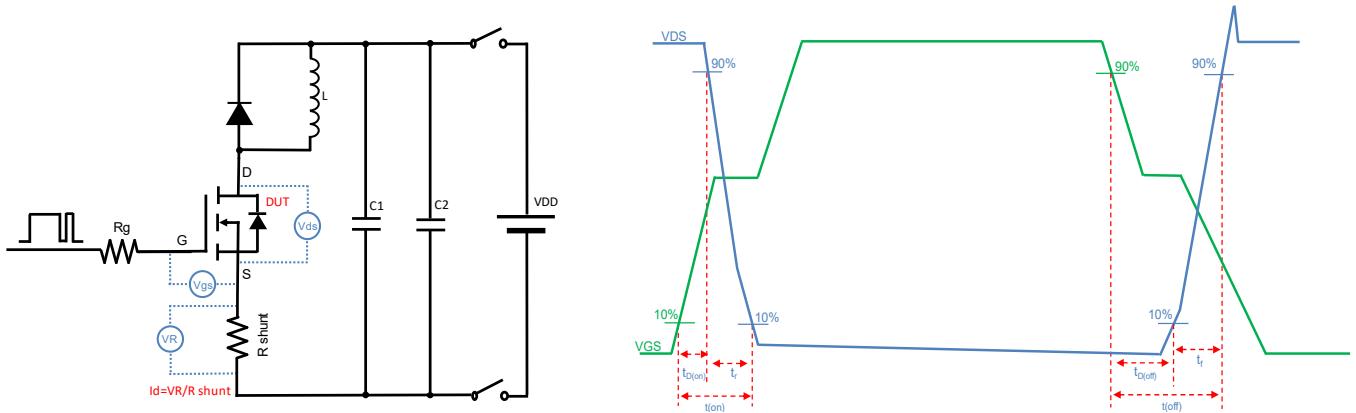


Figure C. Resistive Switching Test Circuit & Waveform

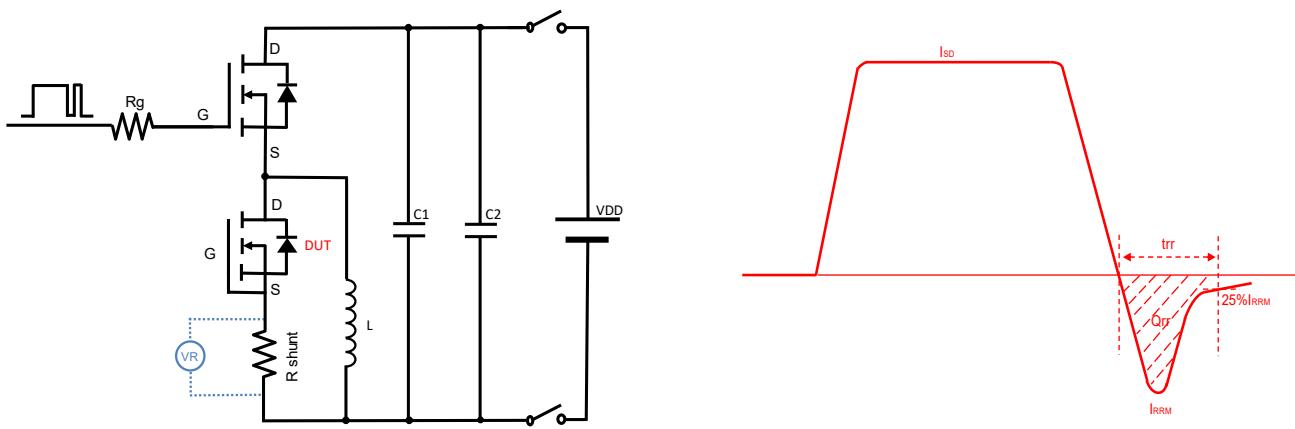
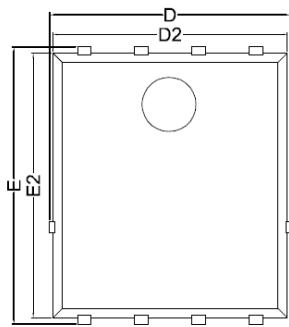
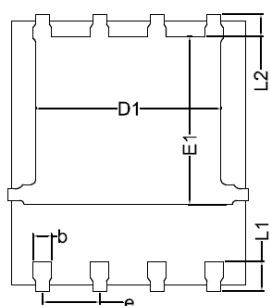
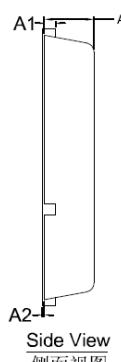
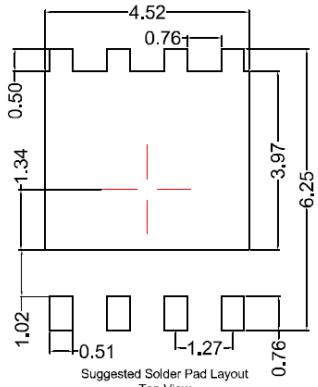


Figure D. Diode Recovery Test Circuit & Waveform



## ■ PDFN5060 Package information

Top View  
正面视图Bottom View  
背面视图Side View  
侧面视图

SYMBOL	MILLIMETER		
	MIN	NOM	MAX
D	5.15	5.35	5.55
E	5.95	6.15	6.35
A	1.00	1.10	1.20
A1		0.254 BSC	
A2			0.10
D1	3.92	4.12	4.32
E1	3.52	3.72	3.92
D2	5.00	5.20	5.40
E2	5.66	5.86	6.06
L1	0.56	0.66	0.76
L2		0.50 BSC	
b	0.31	0.41	0.51
e		1.27 BSC	

## Note:

1. Controlling dimension: in millimeters.
2. General tolerance:  $\pm 0.10\text{mm}$ .
3. The pad layout is for reference purposes only.



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[DMN31D5UDJ-7](#) [DMP22D4UFO-7B](#) [DMN1006UCA6-7](#) [DMN16M9UCA6-7](#) [STF5N65M6](#) [IRF40H233XTMA1](#) [STU5N65M6](#)  
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[BXP2N65D](#) [BXT1150N10J](#) [BXT1700P06M](#) [TSM60NB380CP ROG](#) [RQ7L055BGTCR](#) [DMNH15H110SK3-13](#)